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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	68000
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	20MHz
Co-Processors/DSP	-
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	-55°C ~ 125°C (TC)
Security Features	-
Package / Case	114-BCPGA
Supplier Device Package	114-CPGA (34.54x34.54)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts68020mr1-20

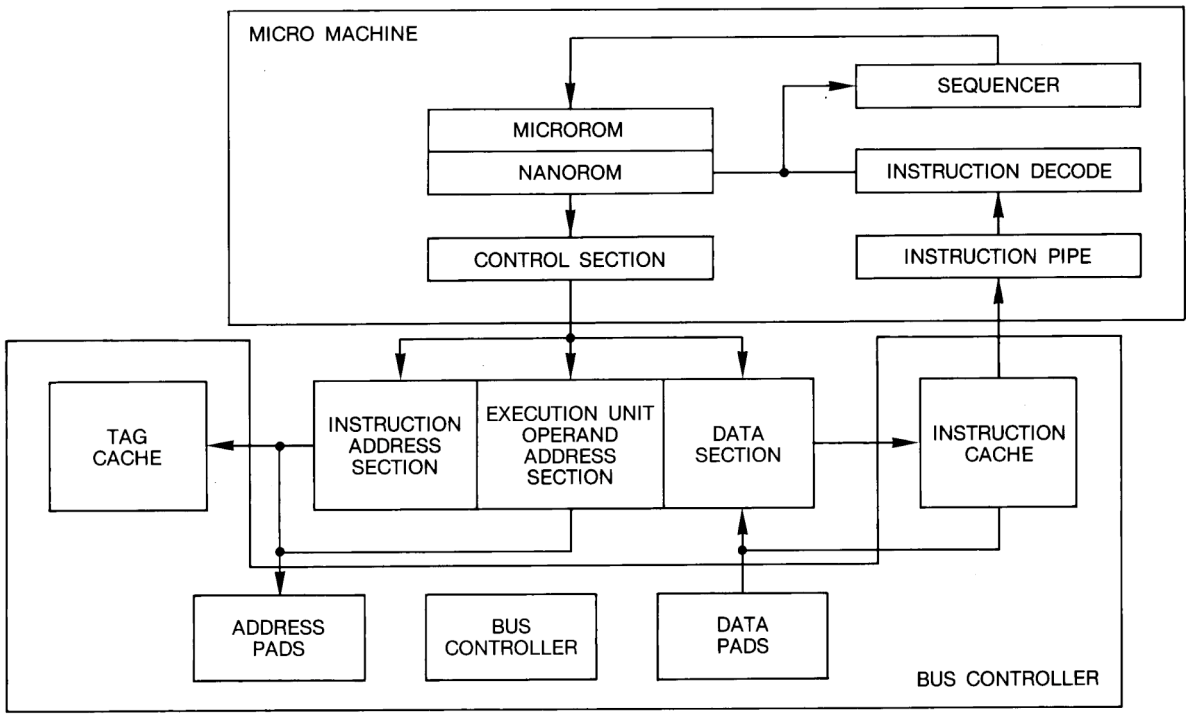
Introduction

The TS68020 is a high-performance 32-bit microprocessor. It is the first microprocessor to have evolved from a 16-bit machine to a full 32-bit machine that provides 32-bit address and data buses as well as 32-bit internal structures. Many techniques were utilized to improve performance and at the same time maintain compatibility with other processors of the TS68000 Family. Among the improvements are new addressing modes which better support high-level language structures, an expanded instruction set which provides 32-bit operations for the limited cases not supported by the TS68000 and several new instructions which support new data types. For special-purpose applications when a general-purpose processor alone is not adequate, a co-processor interface is provided.

The TS68020 is a high-performance microprocessor implemented in HCMOS, low power, small geometry process. This process allows CMOS and HMOS (high density NMOS) gates to be combined on the same device. CMOS structures are used where speed and low power is required, and HMOS structures are used where minimum silicon area is desired. This technology enables the TS68020 to be very fast while consuming less power (less than 1.5 watts) and still have a reasonably small die size. It utilizes about 190.000 transistors, 103.000 of which are actually implemented. The package is a pin-grid array (PGA) with 114 pins, arranged 13 pins on a side with a depopulated center and 132 pins ceramic quad flat pack.

Figure 1 is a block diagram of the TS68020. The processor can be divided into two main sections: the bus controller and the micromachine. This division reflects the autonomy with which the sections operate.

Figure 1. TS68020 Block Diagram



The bus controller consists of the address and data pads and multiplexers required to support dynamic bus sizing, a macro bus controller which schedules the bus cycles on the basis of priority with two state machines (one to control the bus cycles for operated accesses and the other to control the bus cycles for instruction accesses), and the instruction cache with its associated control.

Table 1. Signal Index

Signal Name	Mnemonic	Function
Address Bus	A0-A31	32-bit Address Bus Used to address any of 4, 294, 967, 296 bytes.
Data Bus	D0-D31	32-bit Data Bus Used to Transfer 8, 16, 24 or 32 bits of Data Per Bus Cycle.
Function Codes	FC0-FC2	3-bit Function Case Used to Identify the Address Space of Each Bus Cycle.
Size	SIZ0/SIZ1	Indicates the Number of Bytes Remaining to be Transferred for this Cycle. These Signals, Together with A0 And A1, Define the Active Sections of the Data Bus.
Read-Modify-Write Cycle	$\overline{RMC}$	Provides an Indicator that the Current Bus Cycle is Part of an Indivisibleread-modify-write Operation.
External Cycle Start	$\overline{ECS}$	Provides an Indication that a Bus Cycle is Beginning.
Operand Cycle Start	$\overline{OCS}$	Identical Operation to that of ECS Except that OCS Is Asserted Only During the First Bus Cycle of an Operand Transfer.
Address Strobe	$\overline{AS}$	Indicates that a Valid Address is on The Bus.
Data Strobe	$\overline{DS}$	Indicates that Valid Data is to be Placed on the Data Bus by an External Device or has been Laced on the Data Bus by the TS68020.
Read/Write	R/$\overline{W}$	Defines the Bus Transfer as an MPU Read or Write.
Data Buffer Enable	$\overline{DBEN}$	Provides an Enable Signal for External Data Buffers.
Data Transfer and Size Acknowledge	$\overline{DSACK0}$/$\overline{DSACK1}$	Bus Response Signals that Indicate the Requested Data Transfer Operation is Completed. In Addition, these Two Lines Indicate the Size of the External Bus Port on a Cycle-by-cycle Basis.
Cache Disable	$\overline{CDIS}$	Dynamically Disables the On-chip Cache to Assist Emulator Support.
Interrupt Priority Level	$\overline{IPL0}$-$\overline{IPL2}$	Provides an Encoded Interrupt Level to the Processor.
Autovector	$\overline{AVEC}$	Requests an Autovector During an Interrupt Acknowledge Cycle.
Interrupt Pending	$\overline{IPEND}$	Indicates that an Interrupt is Pending.
Bus Request	$\overline{BR}$	Indicates that an External Device Requires Bus Mastership.
Bus Grant	$\overline{BG}$	Indicates that an External Device may Assume Bus Mastership.
Bus Grant Acknowledge	$\overline{BGACK}$	Indicates that an External Device has Assumed Bus Mastership.
Reset	$\overline{RESET}$	System Reset.
Halt	$\overline{HALT}$	Indicates that the Processor Should Suspend Bus Activity.
Bus Error	$\overline{BERR}$	Indicates an Invalid or Illegal Bus Operation is Being Attempted.
Clock	CLK	Clock Input to the Processor.
Power Supply	V_{CC}	+5-volt ± 10% Power Supply.
Ground	GND	Ground Connection.

Detailed Specifications

Scope

This drawing describes the specific requirements for the microprocessor 68020, 16.67 MHz, 20 MHz and 25 MHz, in compliance with the MIL-STD-883 class B.

Applicable Documents

MIL-STD-883

- MIL-STD-883: Test Methods and Procedures for Electronics
- MIL-PRF-38535 appendix A: General Specifications for Microcircuits
- Desc Drawing 5962 - 860320xxx

Requirements

General

The microcircuits are in accordance with the applicable document and as specified herein.

Design and Construction

Terminal Connections

Depending on the package, the terminal connections shall be as shown in Figure 2 and Figure 3.

Lead Material and Finish

Lead material and finish shall be any option of MIL-STD-1835.

Package

The macrocircuits are packages in hermetically sealed ceramic packages which are conform to case outlines of MIL-STD-1835 (when defined):

- 114-pin SQ.PGA UP PAE Outline
- 132-pin Ceramic Quad Flat Pack CQFP

The precise case outlines are described on Figure 23 and Figure 24.

Electrical Characteristics

Table 2. Absolute Maximum Ratings

Symbol	Parameter	Test Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		-0.3	+7.0	V
V_I	Input Voltage		-0.5	+7.0	V
P_{dmax}	Max Power Dissipation	T_{case} = -55°C		2.0	W
		T_{case} = +125°C		1.9	W
T_{case}	Operating Temperature	M Suffix	-55	+125	°C
		V Suffix	-40	+85	°C
T_{stg}	Storage Temperature		-55	+150	°C
T_{leads}	Lead Temperature	Max 5 Sec. Soldering		+270	°C

Table 3. Recommended Condition of Use

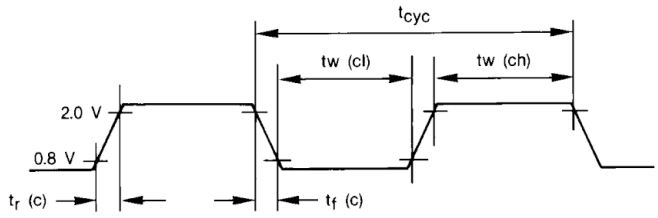
Unless otherwise stated, all voltages are referenced to the reference terminal (see Table 1).

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage		4.5	5.5	V
V_{IL}	Low Level Input Voltage		-0.3	0.5	V
V_{IH}	High Level Input Voltage		2.4	5.25	V
T_{case}	Operating Temperature		-55	+125	°C
R_L	Value of Output Load Resistance		(1)		Ω
C_L	Output Loading Capacitance			(1)	pF
$t_r(c)$–$t_f(c)$	Clock Rise Time (See Figure 5)	68020-16		5	ns
		68020-20		5	
		68020-25		4	
f_c	Clock Frequency (See Figure 5)	68020-16	8	16.67	MHz
		68020-20	12.5	20	
		68020-25	12.5	25	
t_{cyc}	Cycle Time (see Figure 5)	68020-16	60	125	ns
		68020-20	50	80	
		68020-25	40	80	
$t_W(CL)$	Clock Pulse Width Low (See Figure 5)	68020-16	24	95	ns
		68020-20	20	54	
		68020-25	19	61	
$t_W(CH)$	Clock Pulse Width High (See Figure 5)	68020-16	24	95	ns
		68020-20	20	50	
		68020-25	19	61	

Note: 1. Load network number 1 to 4 as specified (Table 7) gives the maximum loading of the relevant output.

This device contains protective circuitry against damage due to high static voltages or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either GND or V_{CC}).

Figure 5. Clock Input Timing Diagram



Note: Timing measurements are referenced to and from a low voltage of 0.8V and a high voltage of 2.0V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8V and 2.0V.

Table 4. Thermal Characteristics at 25°C

Package	Symbol	Parameter	Value	Unit
PGA 114	θ_{JA}	Thermal Resistance - Ceramic Junction to Ambient	26	°C/W
	θ_{JC}	Thermal Resistance - Ceramic Junction to Case	5	°C/W
CQFP 132	θ_{JA}	Thermal Resistance - Ceramic Junction to Ambient	34	°C/W
	θ_{JC}	Thermal Resistance - Ceramic Junction to Case	2	°C/W

Power Considerations

The average chip-junction temperature, T_J, in °C can be obtained from:

$$T_J = T_A + (P_D \cdot \theta_{JA}) \quad (1)$$

T_A = Ambient Temperature, °C

θ_{JA} = Package Thermal Resistance, Junction-to-Ambient, °C/W

$P_D = P_{INT} + P_{I/O}$

$P_{INT} = I_{CC} \cdot V_{CC}$, Watts — Chip Internal Power

$P_{I/O}$ = Power Dissipation on Input and Output Pins — User Determined

For most applications $P_{I/O} < P_{INT}$ and can be neglected.

An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K + (T_J + 273) \quad (2)$$

Solving equations (1) and (2) for K gives:

$$K = P_D \cdot (T_A + 273) + \theta_{JA} \cdot P_D^2 \quad (3)$$

where K is a constant pertaining to the particular part K can be determined from equation **(3)** by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving equations **(1)** and **(2)** iterativley for any value of T_A.

The total thermal resistance of a package (θ_{JA}) can be separated into two components, θ_{JC} and θ_{CA}, representing the barrier to heat flow from the semiconductor junction to the package (case), surface (θ_{JC}) and from the case to the outside ambient (θ_{CA}). These terms are related by the equation:

$$\theta_{JA} = \theta_{JC} = \theta_{CA} \quad (4)$$

θ_{JC} is device related and cannot be influenced by the user. However, θ_{CA} is user dependent and can be minimized by such thermal management techniques as heat sinks, ambient air cooling and thermal convection. Thus, good thermal management on the part of the user can significantly reduce θ_{CA} so that θ_{JA} approximately equals θ_{JC}. Substitution of θ_{JC} for θ_{JA} in equation **(1)** will result in a lower semiconductor junction temperature.

Mechanical and Environment

The microcircuits shall meet all mechanical environmental requirements of MIL-STD-883 for class B devices.

Marking

The document where are defined the marking are identified in the related reference documents. Each microcircuit are legible and permanently marked with the following information as minimum:

- ATMEL Logo
- Manufacturer's Part Number
- Class B Identification
- Date-code of Inspection Lot
- ESD Identifier if Available
- Country of Manufacturing

Quality Conformance Inspection

DESC/MIL-STD-883

Is in accordance with MIL-M-38510 and method 5005 of MIL-STD-883. Group A and B inspections are performed on each production lot. Group C and D inspections are performed on a periodical basis.

Electrical Characteristics

General Requirements

All static and dynamic electrical characteristics specified and the relevant measurement conditions are given below.

(last issue on request to our marketing services).

Table 5: Static electrical characteristics for all electrical variants.

Table 6: Dynamic electrical characteristics for 68020-16 (16.67 MHz), 68020-20 (20 MHz) and 68020-25 (25 MHz).

For static characteristics, test methods refer to "Test Conditions Specific to the Device" on page 14 hereafter of this specification (Table 7).

Input and Output Signals for Dynamic Measurements

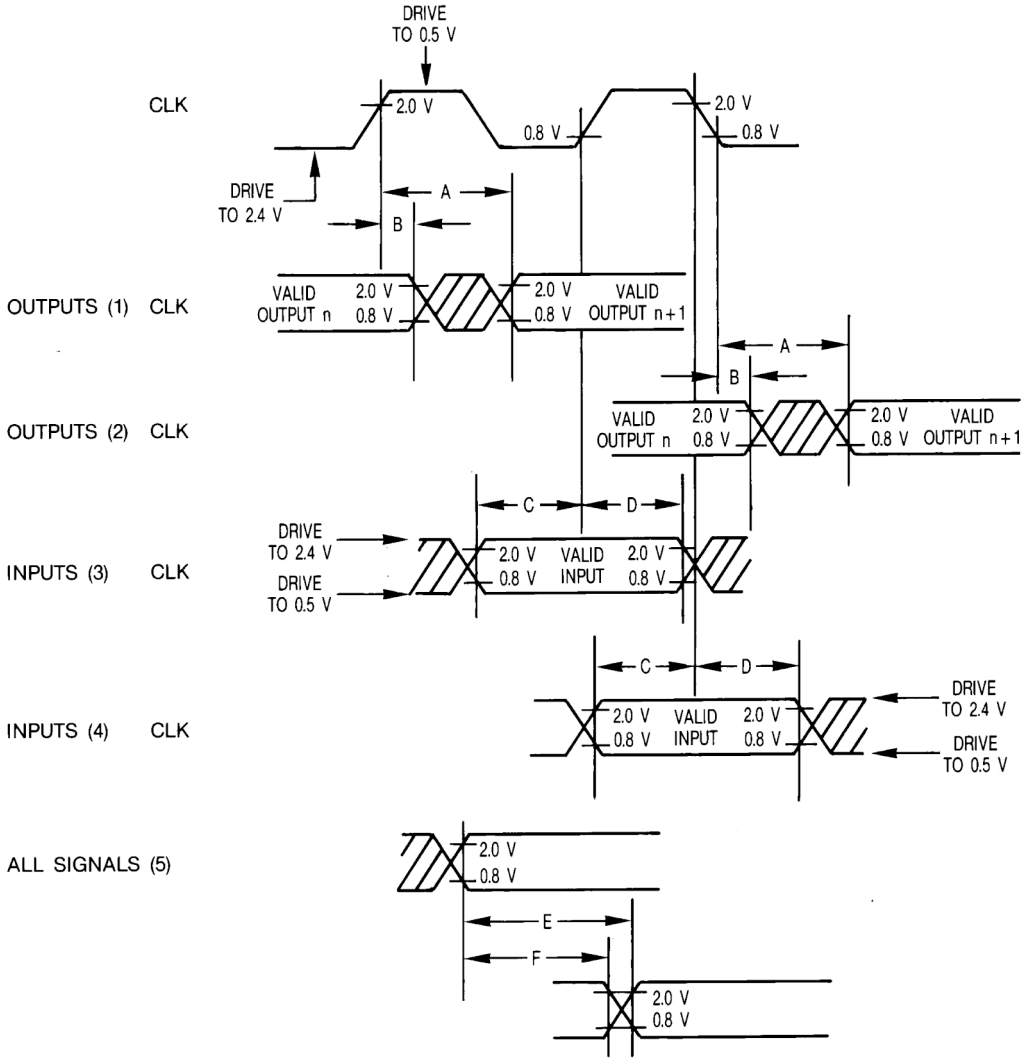
AC Electrical Specifications Definitions

The AC specifications presented consist of output delays, input setup and hold times, and signal skew times. All signals are specified relative to an appropriate edge of the TS68020 clock input and, possibly, relative to one or more other signals.

The measurement of the AC specifications is defined by the waveforms in Figure 12. In order to test the parameters guaranteed by Atmel, inputs must be driven to the voltage levels specified in Figure 12. Outputs of the TS68020 are specified with minimum and/or maximum limits, as appropriate, and are measured as shown. Inputs to the TS68020 are specified with minimum and, as appropriate, maximum setup and hold times, and are measurement as shown. Finally, the measurements for signal-to-signal specification are also shown.

Note that the testing levels used to verify conformance of the TS68020 to the AC specifications does not affect the guaranteed DC operation of the device as specified in the DC electrical characteristics.

Figure 12. Drive Levels and Test Points for AC Specification



Legend:

A) Maximum Output Delay Specification

B) Minimum Output Hold Time

C) Minimum Input Setup Time Specification

D) Minimum Input Hold Time Specification

E) Signal Valid to Signal Valid Specification (Maximum or Minimum)

F) Signal Valid to Signal Invalid Specification (Maximum or Minimum)

Notes:
1. This output timing is applicable to all parameters specified relative to the rising edge of the clock.
2. This out put timing is applicable to all parameters specified relative to the falling edge of the clock.
3. This input timing is applicable to all parameters specified relative to the falling edge of the clock.
4. This input timing is applicable to all parameters specified relative to the falling edge of the clock.
5. This timing is applicable to all parameters specified relative to the assertion/negation of another signal.

Figure 14. ECS and OCS Capacitance Derating Curve

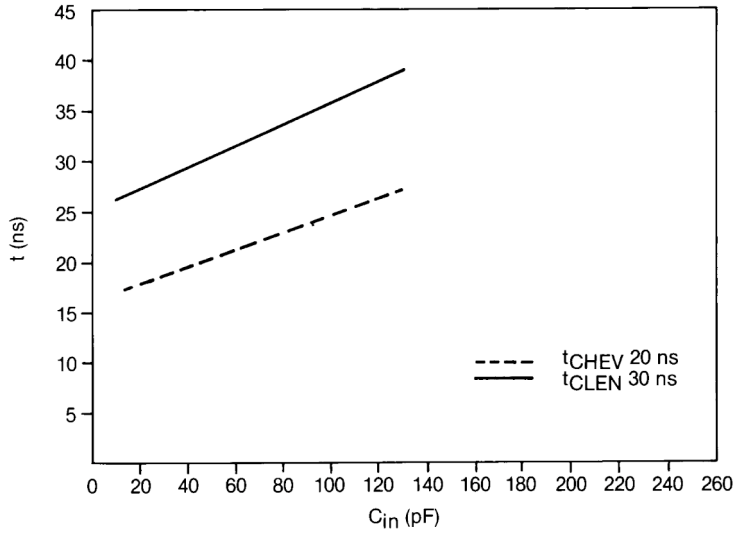


Figure 15. R/W, FC, SIZ0-SIZ1, and RMC Capacitance Derating Curve

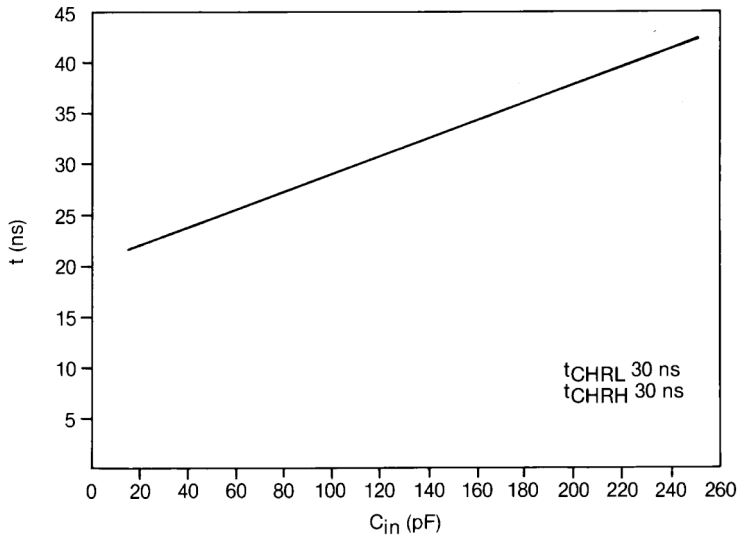


Figure 16. DS, AS, IPEND, and BG Capacitance Derating Curve

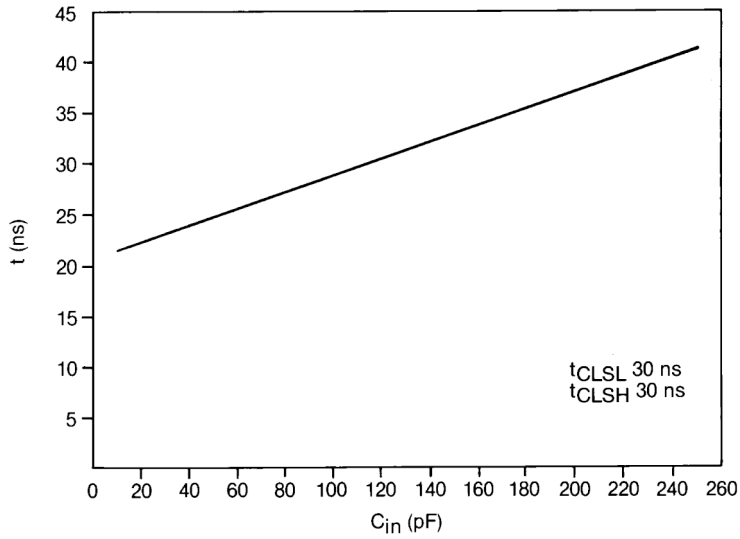


Figure 17. DBEN Capacitance Derating Curve

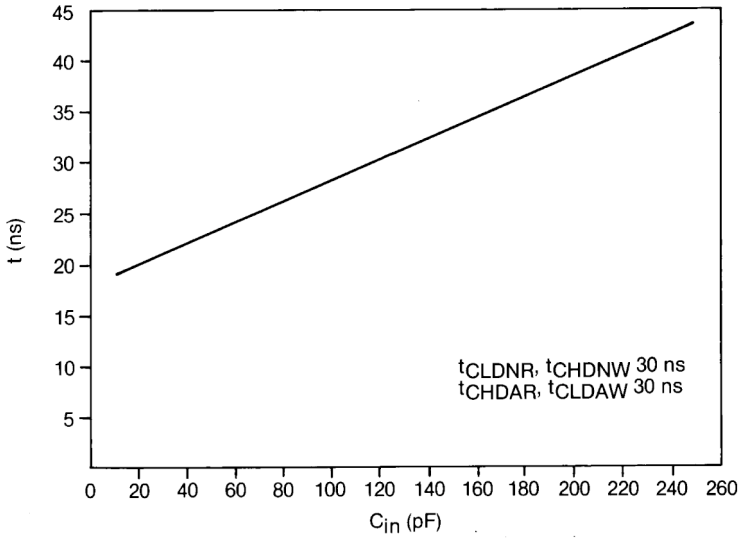
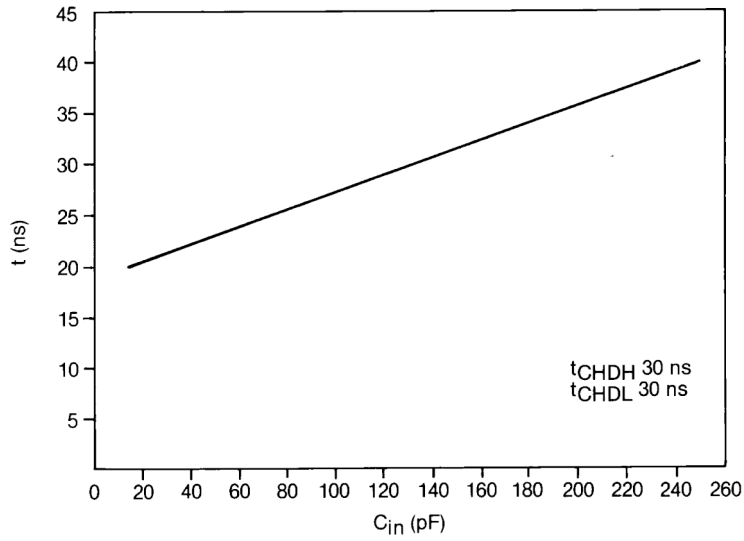


Figure 18. Data Capacitance Derating Curve



Functional Description

Description of Registers

As shown in the programming models (Figure 19 and Figure 20) the TS68020 has sixteen 32-bit general-purpose registers, a 32-bit program counter, two 32-bit supervisor stack pointers, a 16-bit status register, a 32-bit vector base register, two 3-bit alternate function code registers, and two 32-bit cache handling (address and control) registers. Registers D0-D7 are used as data registers for bit and bit field (1- to 32-bit), byte (8-bit), long word (32-bit), and quad word (64-bit) operations. Registers A0-A6 and the user, interrupt, and master stack pointers are address registers that may be used as software stack pointers or base address registers. In addition, the address registers may be used for word and long word operations. All of the 16 (D0-D7, A0-A7) registers may be used as index registers.

The status register (Figure 21) contains the interrupt priority mask (three bits) as well as the condition codes: extend (X), negated (N), zero (Z), overflow (V), and carry (C). Additional control bits indicate that the processor is in the trace mode (T1 or T0), supervisor/user state (S), and master/interrupt state (M).

All microprocessors of the TS68000 Family support instruction tracing (via the T0 status bit in the TS68020) where each instruction executed is followed by a trap to a user-defined trace routine. The TS68020 adds the capability to trace only the change of flow instructions (branch, jump, subroutine call and return, etc.) using the T1 status bit. These features are important for software program development and debug.

The vector base register is used to determine the runtime location of the exception vector table in memory, hence it supports multiple vector tables so each process or task can properly manage exceptions independent of each other.

The 18 addressing modes, shown in Table 8, include nine basic types:

- Register Direct
- Register Indirect
- Register Indirect with Index
- Memory Indirect
- Program Counter Indirect with Displacement
- Program Counter Indirect with Index
- Program Counter Memory Indirect
- Absolute
- Immediate

The register indirect addressing modes support postincrement, predecrement, offset, and indexing. Programmers find these capabilities particularly useful for handling advanced data structures common to sophisticated applications and high level languages. The program counter relative mode also has index and offset capabilities; programmers find that this addressing mode is required to support position-independent software. In addition to these addressing modes, the TS68020 provides data operand sizing and scaling; these features provide performance enhancements to the programmer.

Table 8. TS68020 Addressing Modes

Addressing Modes	Syntax
Register Direct	
Data Register Direct	Dn
Address Register Direct	An
Register Indirect	
Address Register Indirect	(An)
Address Register Indirect with Post Increment	(An) +
Address Register Indirect with Predecrement	– (An)
Address Register Indirect with Displacement	(d_{16}An)
Register Indirect with Index	
Address Register Indirect with Index (8-bit Displacement)	(d_8, An, Xn)
Address Register Indirect with Index (Base Displacement)	(bd, An, Xn)
Memory Indirect	
Memory Indirect Post-Indexed	([bd, An], Xn, od)
Memory Indirect Pre-Indexed	([bd, An, Xn], od)
Program Counter Indirect with Displacement	(d_{16}, PC)
Program Counter Indirect with Index	
PC Indirect with Index (8-bit Displacement)	(d_8, PC, Xn)
PC Indirect with Index (Base Displacement)	(bd, PC, Xn)
Program Counter Memory Indirect	
PC Memory Indirect Post-Indexed	([bd, PC], Xn, od)
PC Memory Indirect Pre-Indexed	([bd, PC, Xn]), od)

Table 9. Instruction Set (Continued)

Mnemonic	Description
CALLM	Call Module
CAS	Compare and Swap Operands
CAS2	Compare and Swap Dual Operands
CHK	Check Register Against Bound
CHK2	Check Register Against Upper and Lower Bounds
CLR	Clear
CMP	Compare
CMPA	Compare Address
CMPI	Compare Immediate
CMPM	Compare Memory to Memory
CMP2	Compare Register Against Upper and Lower Bounds
DBcc	Test Condition, Decrement and Branch
DIVS, DIVSL	Signed Divide
DIVU, DIVUL	Unsigned Divide
EOR	Logical Exclusive OR
EORI	Logical Exclusive OR Immediate
EXG	Exchange Registers
EXT, EXTB	Sign Extend
ILLEGAL	Take Illegal Instruction Tape
JMP	Jump
JSR	Jump to Subroutine
LEA	Load Effective Address
LINK	Link and Allocate
LSL, LSR	Logical Shift Left and Right
MOVE	Move
MOVEA	Move Address
MOVE CCR	Move Condition Code Register
MOVE SR	Move Status Register
MOVE USP	Move User Stack Pointer
MOVEC	Move Control Register
MOVEM	Move Multiple Registers
MOVEP	Move Peripheral
MOVEQ	Move Quick
MOVES	Move Alternate Address Space
MULS	Signed Multiply
MULU	Unsigned Multiply
NBCD	Negate Decimal with Extend
NEG	Negate
NEGX	Negate with Extend
NOP	No Operation
NOT	Logical Complement

Table 11. Co-processor Primitives (Continued)

General Operand Transfer
Evaluate and Pass (Ea.)
Evaluate (Ea.) and Transfer Data
Write to Previously Evaluated (Ea.)
Take Address and Transfer Data
Transfer to/from Top of Stack
Register Transfer
Transfer CPU Register
Transfer CPU Control Register
Transfer Multiple CPU Registers
Transfer Multiple Co-processor Registers
Transfer CPU SR and/or ScanPC

Up to eight processors are supported in a single system with a system-unique co-processor identifier encoded in the co-processor instruction. When accessing a co-processor, the TS68020 executes standard read and write bus cycle in CPU address space, as encoded by the function codes, and places the co-processor identifier on the address bus to be used by chip-select logic to select the particular co-processor. Since standard bus cycle are used to access the co-processor, the co-processor may be located according to system design requirements, whether it be located on the micro-processor local bus, on another board on the system bus, or any other place where the chip-select and co-processor protocol using standard TS68000 bus cycles can be supported.

Co-processor Protocol

Interprocessor transfers are all initiated by the main processor during co-processor instruction execution. During the processing of a co-processor instruction, the main processor transfers instruction information and data to the associated co-processor, and receives data, requests, and status information from the co-processor. These transfers are all based on the TS68000 bus cycles.

The typical co-processor protocol which the main processor follows is:

a) The main processor initiates the communications by writing command information to a location in the co-processor interface.

b) The main processor reads the co-processor response to that information.

1) The response may indicate that the co-processor is busy, and the main processor should again query the co-processor. This allows the main processor and co-processor to synchronize their concurrent operations.

2) The response may indicate some exception condition; the main processor acknowledges the exception and begins exception processing.

3) The response may indicate that the co-processor needs the main processor to perform some service such as transferring data to or from the co-processor. The co-processor may also request that the main processor query the co-processor again after the service is complete.

4) The response may indicate that the main processor is not needed for further processing of the instruction. The communication is terminated, and the main processor is free to begin execution of the next instruction. At this point in the co-processor protocol, as the main processor continues to execute the instruction stream, the main processor may operate concurrently with the co-processor.

The TS68020 provides an extension to the exception stacking process. If the M bit in the status register is set, the master stack pointer (MSP) is used for all task related exceptions. When a non-task exception occurs (i.e., an interrupt), the M bit is cleared and the interrupt stack pointer (ISP) is used. This feature allows all the task's stack area to be carried within a single processor control block and new tasks may be initiated by simply reloading the master stack pointer and setting the M bit.

The fourth and last step of the exception processing is the same for all exceptions. The exception vector offset is determined by multiplying the vector number by four. This offset is then added to the contents of the vector base register (VBR) to determine the memory address of the exception vector. The new program counter value is fetched from the exception vector. The instruction at the address given in the exception vector is fetched, and the normal instruction decoding and execution is started.

On-chip Instruction Cache

Studies have shown that typical programs spend most of their execution time in a few main routines or tight loops. This phenomenon is known as locality of reference, and has an impact on performance of the program. The TS68020 takes limited advantage of this phenomenon in the form of its loop mode operation which allows certain instructions, when coupled with the DBcc instruction, to execute without the overhead of instruction fetches. In effect, this is a three word cache. Although the cache hardware has been supplied in a full range of computer systems for many years, technology now allows this feature to be integrated into the microprocessor.

TS68020 Cache Goals

There were two primary goals for the TS68020 microprocessor cache. The first design goal was to reduce the processor external bus activity. In a given TS68000 system, the TS68000 processor will use approximately 80 to 90 percent (for greater) of the available bus bandwidth. This is due to its extremely efficient perfecting algorithm and the overall speed of its internal architecture design. Thus, in an TS68000 system with more than one bus master (such as a processor and DMA device) or in a multiprocessor system, performance degradation can occur due to lack of available bus bandwidth. Therefore, an important goal for an TS68020 on-chip cache was to provide a substantial increase in the total available bus bandwidth.

The second primary design goal was to increase effective CPU throughput as larger memory sizes or slower memories increased average access time. By placing a high speed cache between the processor and the rest of the memory system, the effective access time now becomes:

$$t_{ACC} = h^{**}t_{CACHE} = (1 - h)^{*}t_{ext}$$

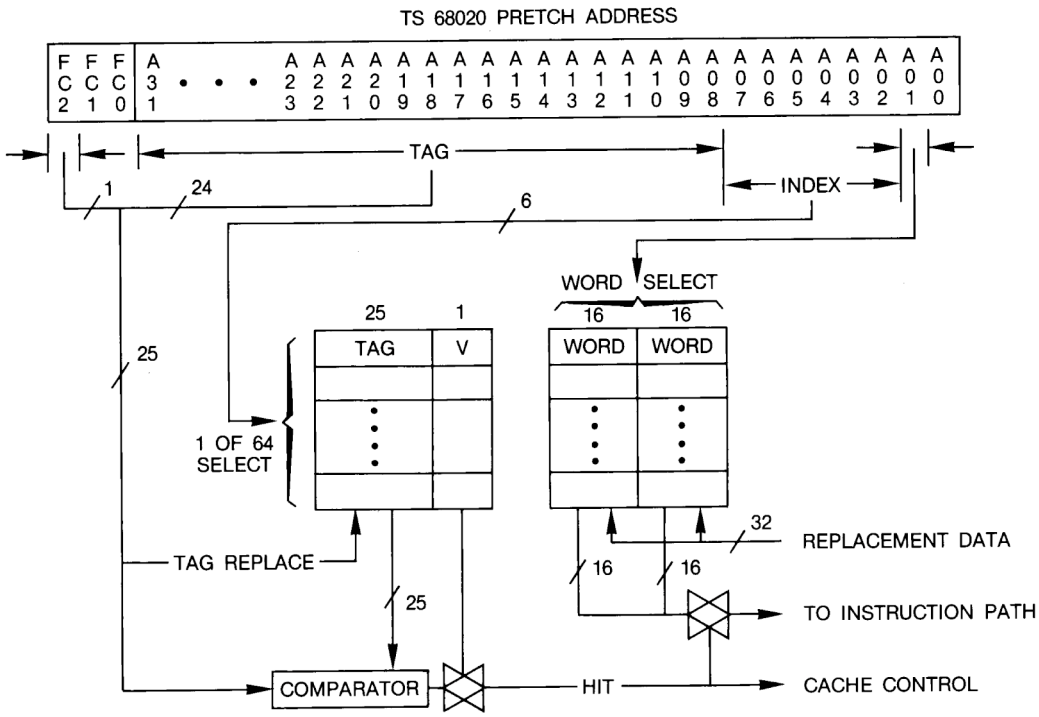
where t_{ACC} is the effective system access time, t_{CACHE} is the cache access time, t_{ext} is the access time of the rest of the system, and h is the hit ratio or the percentage of time that the data is found in the cache. Thus, for a given system design, an TS68020 on-chip cache provides a substantial CPU performance increase, or allows much slower and less expensive memories to be used for the same processor performance.

The throughput increase in the TS68020 is gained in two ways. First, the TS68020 cache is accessed in two clock cycles versus the three cycles (minimum) required for an external access. Any instruction fetch that is currently resident in the cache will provide a 33% improvement over the corresponding external access.

Second, and probably the most important benefit of the cache, is that it allows instruction stream fetches and operand accesses to proceed in parallel. For example, if the TS68020 requires both an instruction stream access and an operand access, and the instruction is resident in the cache, the operand access will proceed unimpeded rather than being queued behind the instruction fetch. Similarly, the TS68020 is fully capable of executing several internal instructions (instructions that do not require the bus) while completing an operand access for another instruction.

The TS68020 instruction cache is a 256-byte direct mapped cache organized as 64 long word entries. Each cache entry consists of a tag field made up of the upper 24 address bits, the FC2 (user/supervisor) value, one valid bit, and 32-bit of instruction data (Figure 22).

Figure 22. TS68020 On-chip Cache Organization



The TS68020 employs a 32-bit data bus and fetches instructions on long word address boundaries. Hence, each 32-bit instruction fetch brings in two 16-bit instruction words which are then written into the on-chip cache. When the cache is enabled, the subsequent prefetch will find the next 16-bit instruction word is already present in the cache and the related bus cycle is saved. If the cache were not enabled, the subsequent prefetch will find the bus controller still holds the full 32-bit and can satisfy the prefetch and again save the related bus cycle. So, even when the on-chip instruction cache is not enabled, the bus controller provides an instruction “cache hit” rate up to 50%.

Preparation for Delivery

Certificate of Compliance

Atmel offers a certificate of compliance with each shipment of parts, affirming the products are in compliance with MIL-STD-883 and guaranteeing the parameters are tested at extreme temperatures for the entire temperature range.

Handling

MOS devices must be handled with certain precautions to avoid damage due to accumulation of static charge. Input protection devices have been designed in the chip to minimize the effect of this static buildup. However, the following handling practices are recommended:

a) Device should be handled on benches with conductive and grounded surface.

b) Ground test equipment, tools and operator

c) Do not handle devices by the leads.

d) Store devices in conductive foam or carriers.

e) Avoid use of plastic, rubber, or silk in MOS areas.

f) Maintain relative humidity above 50%, if practical.

Mass

PGA 114 - 6 grams typically
CQFP 132 - 14 grams typically

Terminal Connections

114-lead - Ceramic Pin Grid Array

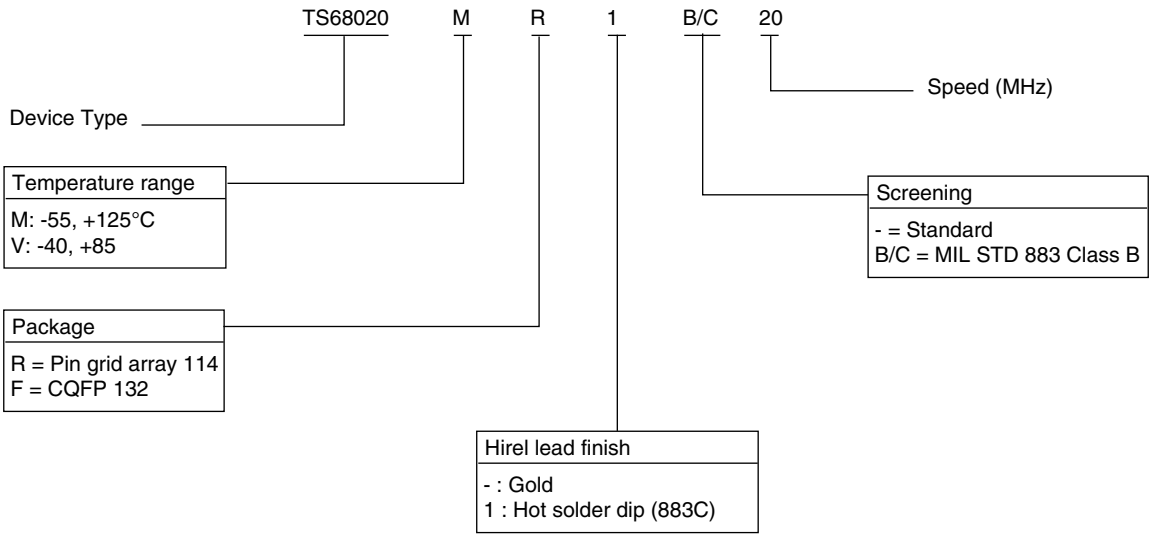
See Figure 2.

132-lead - Ceramic Quad Flat Pack

See Figure 3.

Standard Product

Commercial Atmel Part-Number	Norms	Package	Temperature Range T_c (°C)	Frequency (MHz)	Drawing Number
TS68020VF16	Internal Standard	CQFP 132	-40/+85	16.67	Internal
TS68020VF120	Internal Standard	CQFP 132	-40/+85	20	Internal
TS68020VF25	Internal Standard	CQFP 132	-40/+85	25	Internal
TS68020MF16	Internal Standard	CQFP 132	-55/+125	16.67	Internal
TS68020MF20	Internal Standard	CQFP 132	-55/+125	20	Internal
TS68020MF25	Internal Standard	CQFP 132	-55/+125	25	Internal



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